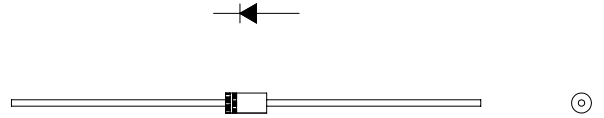


# FRD Type :11DF2

## OUTLINE DRAWING

### FEATURES

- \* Miniature Size
- \* Ultra - Fast Recovery
- \* Low Forward Voltage drop
- \* Low Power Loss, High Efficiency
- \* High Surge Capability
- \* 200 Volts thru 400 Volts Types Available
- \* 52mm Inside Tape Spacing Package Available



### Maximum Ratings

Approx Net Weight:0.33g

Rating	Symbol	11DF2		Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	200		V
Non-repetitive Peak Reverse Voltage	$V_{RSM}$	220		V
Average Rectified Output Current	$I_O$	1.0	Ta=27°C *1 50Hz Half Sine Wave Resistive Load	A
			Ta=63°C *2	
RMS Forward Current	$I_{F(RMS)}$	1.57		A
Surge Forward Current	$I_{FSM}$	30	50Hz Half Sine Wave,1cycle, Non-repetitive	A
Operating JunctionTemperature Range	$T_{jw}$	- 40 to + 150		°C
Storage Temperature Range	$T_{stg}$	- 40 to + 150		°C

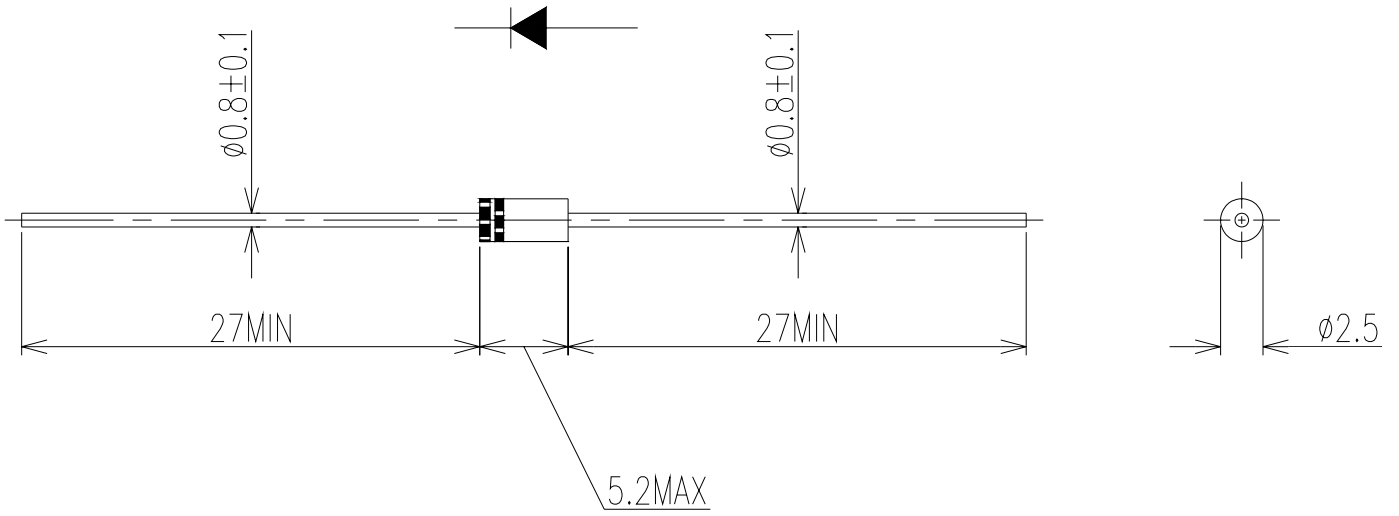
### Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	$I_{RM}$	$T_j = 25^\circ\text{C}$ , $V_{RM} = V_{RRM}$	-	-	10	$\mu\text{A}$
Peak Forward Voltage	$V_{FM}$	$T_j = 25^\circ\text{C}$ , $I_{FM} = 1.0\text{A}$	-	-	0.98	V
Reverse Recovery Time	trr	-di/dt=50A/ $\mu\text{s}$ , $I_{FM}=1\text{A}$ , $T_a=25$	-	-	30	ns
Thermal Resistance	Rth(j-a)	Junction to Ambient	-	-	115	°C/W
					81	

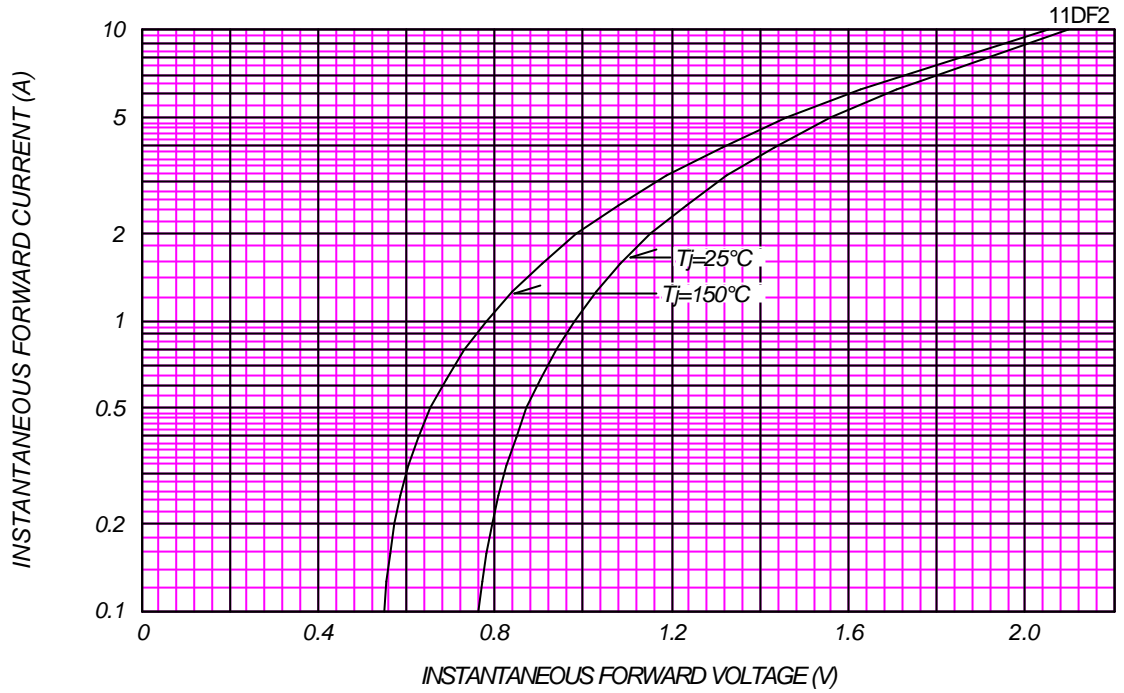
\*1 : Without Fin or P.C. Board

\*2 : P.C. Board mounted(L=8mm,Print Lands =10x10mm,Both Sides)

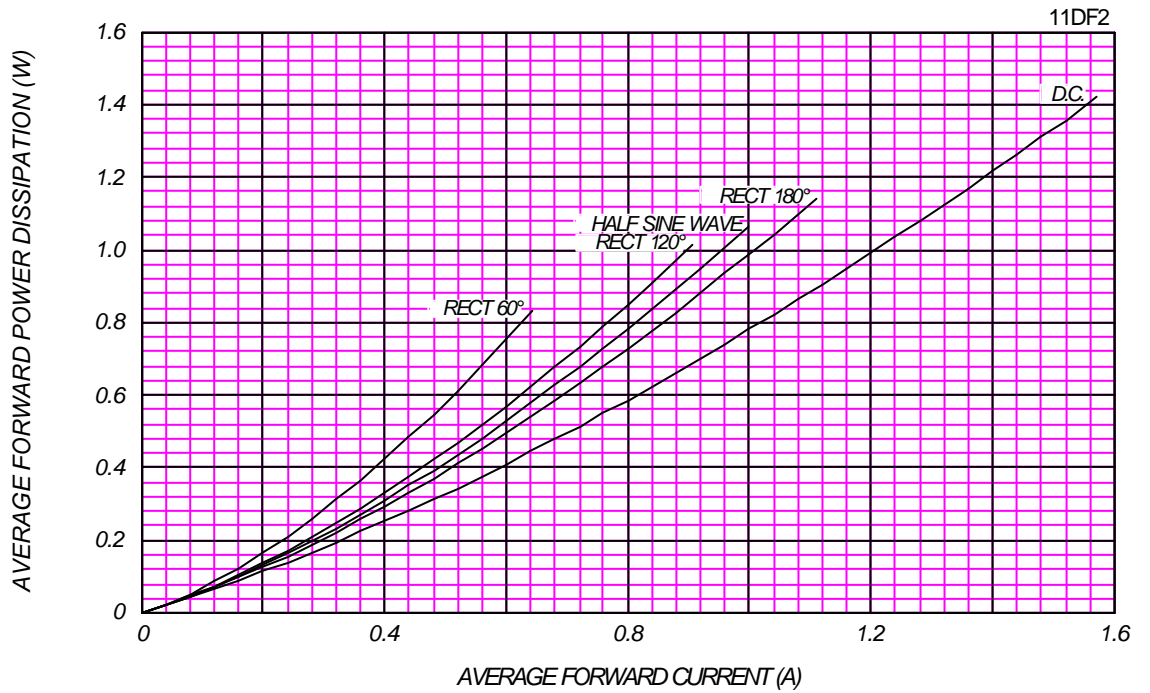
11DF2 OUTLINE DRAWING (Dimensions in mm)



FORWARD CURRENT VS. VOLTAGE



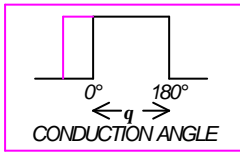
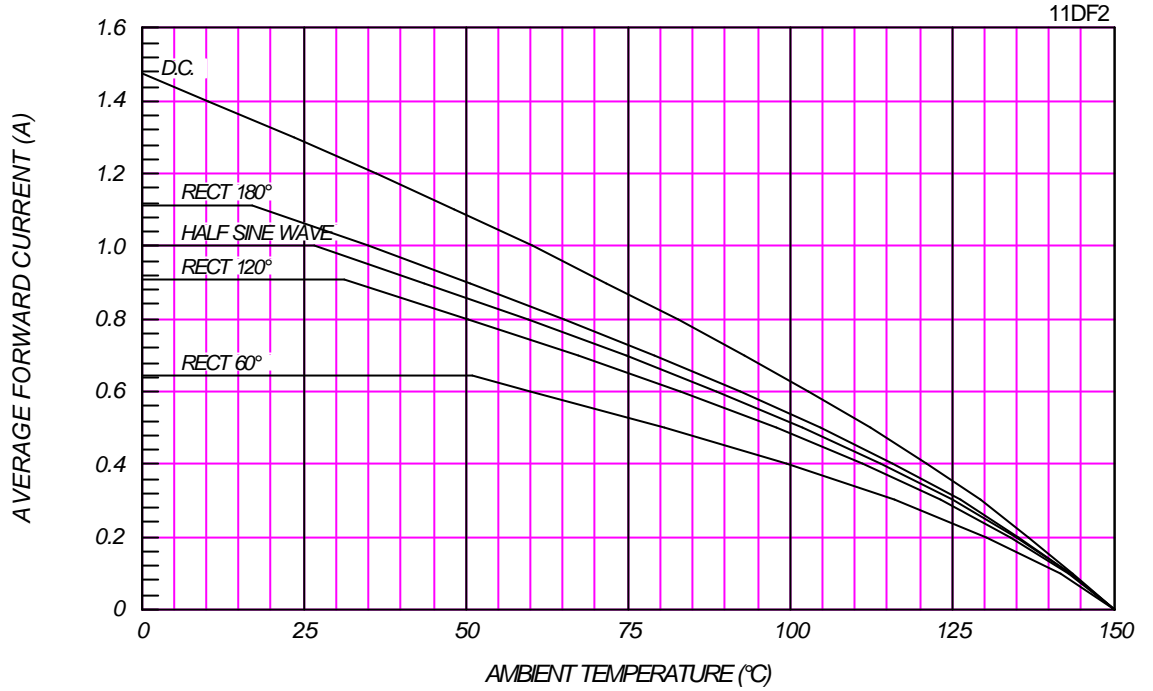
AVERAGE FORWARD POWER DISSIPATION





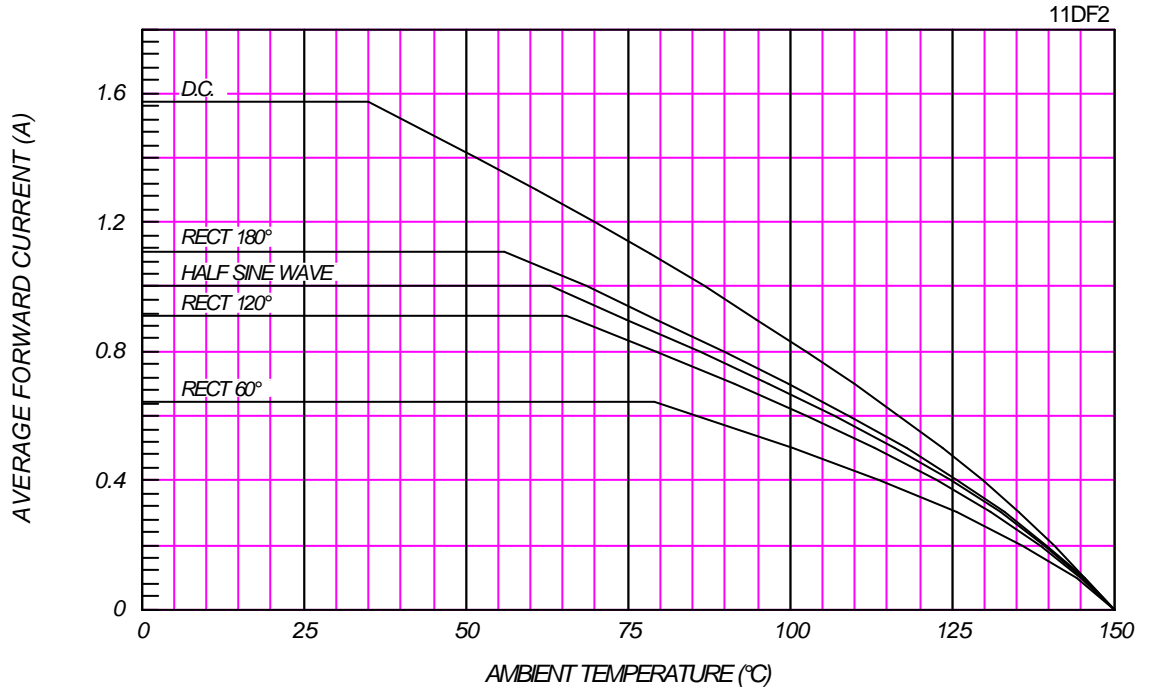
### AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Without Fin or P.C. Board



### AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

P.C. Board mounted (L=8mm, Print Land=10x10mm, Both Sides)



# SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

11DF2

